

Product Summary

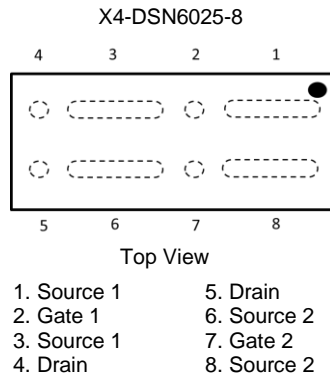
BV _{SS}	R _{SS(ON)} Typ	I _S Max T _A = +25°C
30V	2.2mΩ @ V _{GS} = 10V	28.2A
	2.3mΩ @ V _{GS} = 8V	27.6A
	2.7mΩ @ V _{GS} = 4.5V	25.4A

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{SS(ON)}) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

Applications

- Battery management
- Load switches
- Battery protections

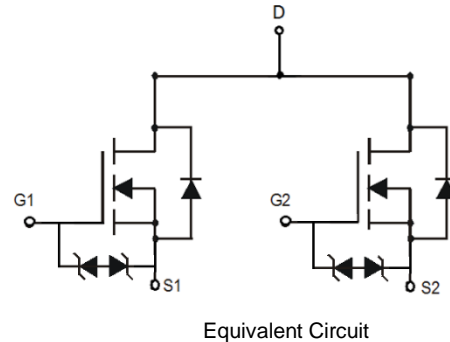


Features

- CSP with Footprint 6mm x 2.5mm
- Height = 0.18mm (Typical) for Low Profile
- ESD Protection of Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)**
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](mailto:contact_us) or your local Diodes representative. <https://www.diodes.com/quality/product-definitions/>**

Mechanical Data

- Package: X4-DSN6025-8
- Terminal Connections: See Diagram Below
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — NiAu. Solderable per MIL-STD-202, Method 208 **(e4)**
- Weight: 0.0012 grams (Approximate)

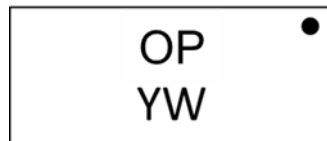


Ordering Information (Note 4)

Orderable Part Number	Package	Packing	
		Qty.	Carrier
DMN32M7LCA8-7	X4-DSN6025-8	3000	Tape & Reel

- Notes:
- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 - See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 - Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 - For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



OP = Product Type Marking Code
 YW = Date Code Marking
 Y or \bar{Y} = Year (ex: 4 = 2024)
 W or \bar{W} = Week (ex: a = Week 27; z Represents Week 52 and 53)

Date Code Key

Year	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034	2035
Code	4	5	6	7	8	9	0	1	2	3	4	5
Week	1-26				27-52				53			
Code	A-Z				a-z				z			

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Source-Source Voltage		V _{SSS}	30	V
Gate-Source Voltage		V _{GSS}	±20	V
Continuous Source Current (Note 5) V _{GS} = 10V	Steady State	I _S	T _A = +25°C 25.9	A
			T _A = +70°C 20.7	
Continuous Source Current (Note 5) V _{GS} = 4.5V	Steady State	I _S	T _A = +25°C 18.5	A
			T _A = +70°C 14.8	
Pulsed Source Current (Note 6)		I _{SM}	135	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 7)	P _D	1.2	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 7)	R _{θJA}	102.5	°C/W
Power Dissipation (Note 5)	P _D	2.6	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 5)	R _{θJA}	47.7	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Source-Source Breakdown Voltage	BV _{SSS}	30	—	—	V	V _{GS} = 0V, I _S = 1mA
Zero Gate Voltage Drain Current T _J = +25°C	I _{SSS}	—	—	1	µA	V _{SS} = 24V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±10	µA	V _{GS} = ±20V, V _{SS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(TH)}	1.3	—	2.2	V	V _{SS} = 10V, I _S = 1mA
Static Source-Source On-Resistance	R _{SS(ON)}	1.5	2.2	2.6	mΩ	V _{GS} = 10V, I _S = 10A
		1.6	2.3	3.3		V _{GS} = 8V, I _S = 10A
		2.2	2.7	5.1		V _{GS} = 4.5V, I _S = 10A
Diode Forward Voltage	V _{SS}	—	—	1.2	V	V _{GS} = 0V, I _S = 10A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{ISS}	—	2447	—	pF	V _{SS} = 15V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{OSS}	—	647	—		
Reverse Transfer Capacitance	C _{RSS}	—	74	—		
Total Gate Charge	Q _G	—	567.3	—	nC	V _{SS} = 15V, V _{GS} = 4.5V I _S = 10A
Gate-Source Charge	Q _{Gs}	—	56.9	—		
Gate-Drain Charge	Q _{Gd}	—	119.9	—		
Gate Charge at V _{TH}	Q _{G(TH)}	—	12.9	—		
Turn-On Delay Time	t _{D(ON)}	—	21.3	—	ns	V _{SS} = 15V, V _{GS} = 4.5V I _S = 10A
Turn-On Rise Time	t _R	—	19	—		
Turn-Off Delay Time	t _{D(OFF)}	—	1421	—		
Turn-Off Fall Time	t _F	—	5257	—		

- Notes:
5. Device mounted on FR-4 material with 1inch² (6.45cm²), 2oz. (0.071mm thick) Cu.
 6. Repetitive rating, pulse width limited by junction temperature.
 7. Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
 8. Short duration pulse test used to minimize self-heating effect.
 9. Guaranteed by design. Not subject to production testing.

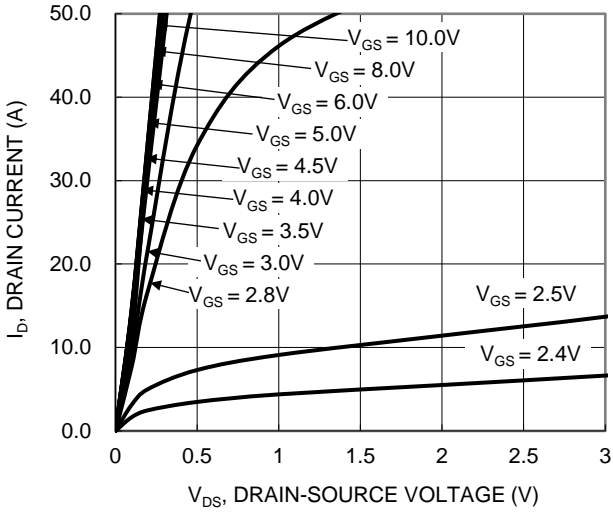


Figure 1. Typical Output Characteristic

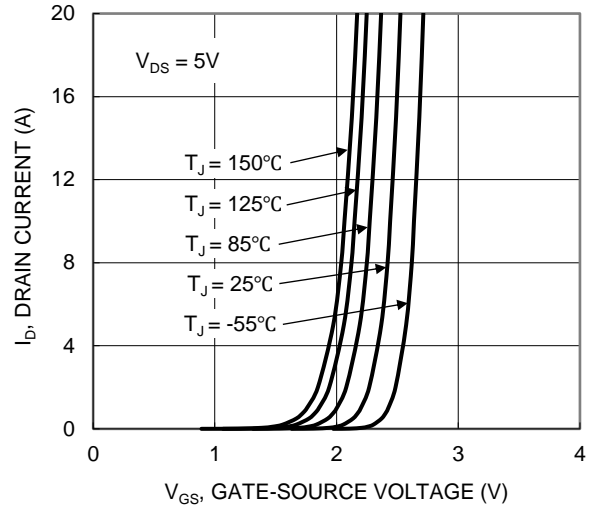


Figure 2. Typical Transfer Characteristic

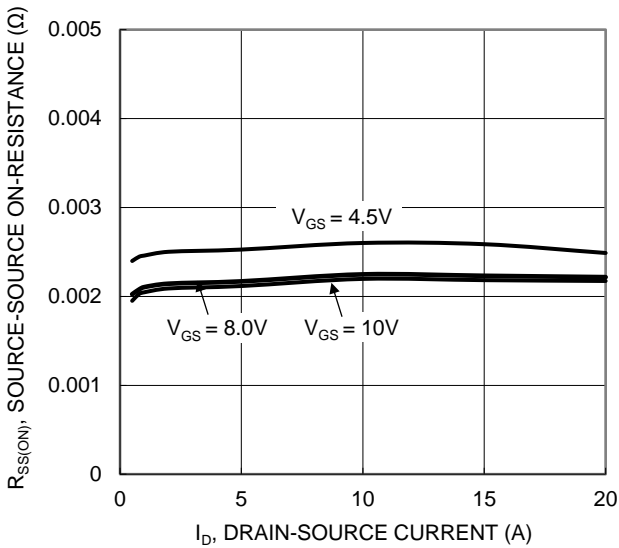


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

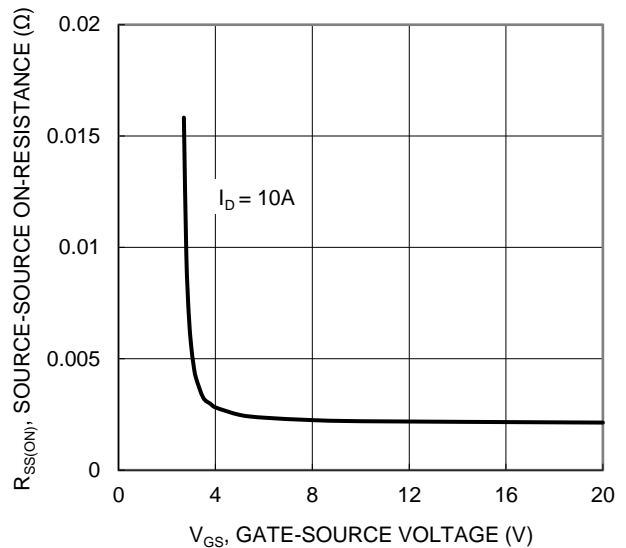


Figure 4. Typical Transfer Characteristic

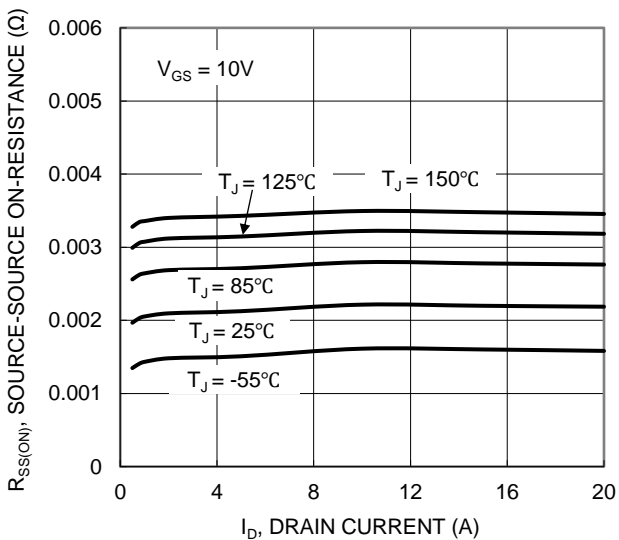


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

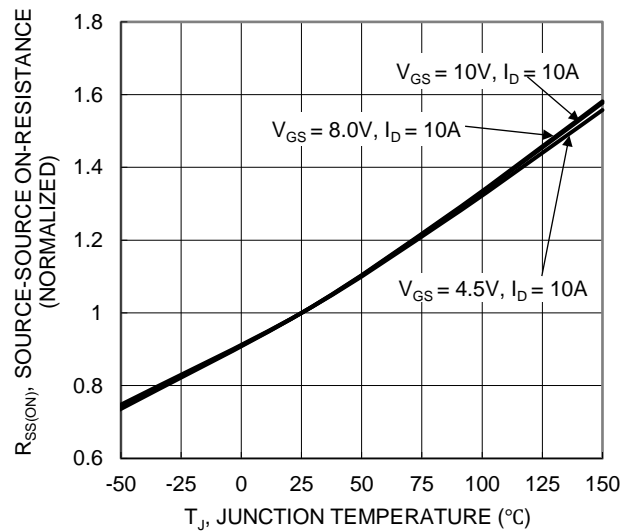


Figure 6. On-Resistance Variation with Junction Temperature

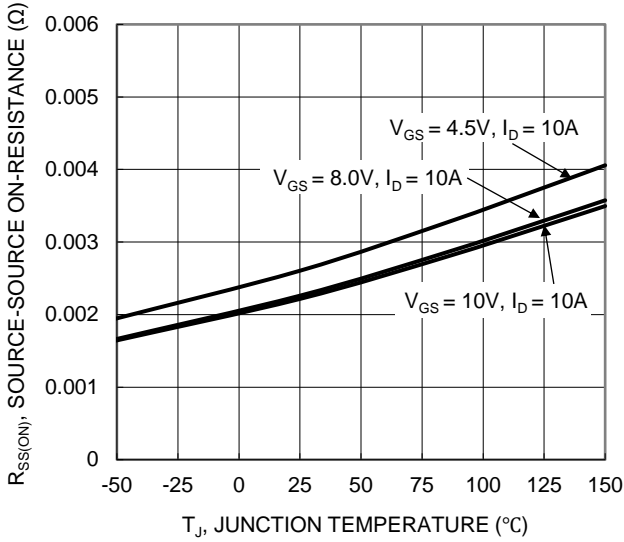


Figure 7. On-Resistance Variation with Junction Temperature

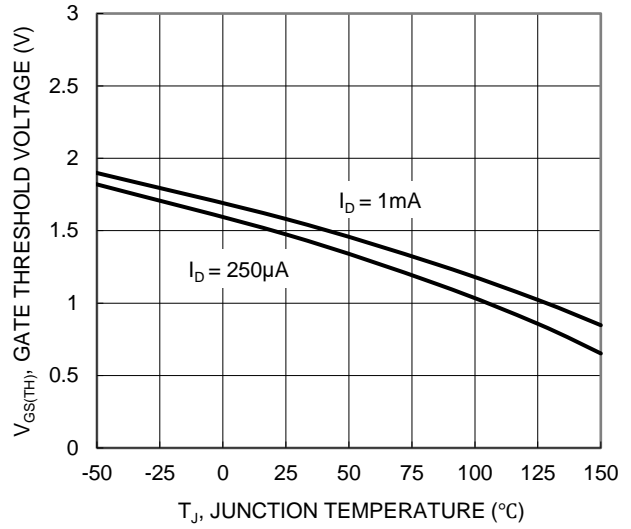


Figure 8. Gate Threshold Variation vs. Junction Temperature

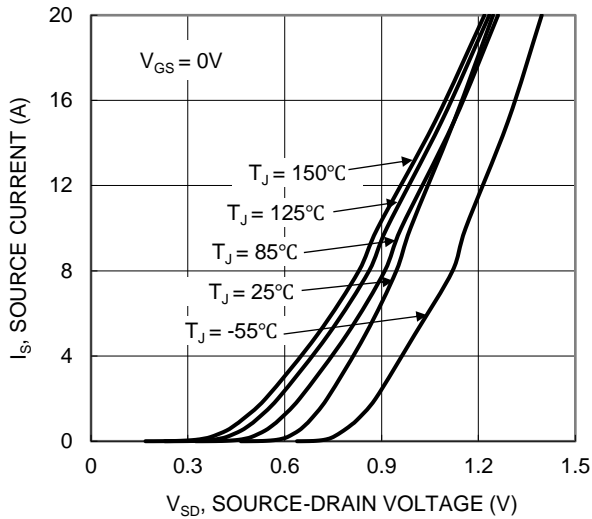


Figure 9. Diode Forward Voltage vs. Current

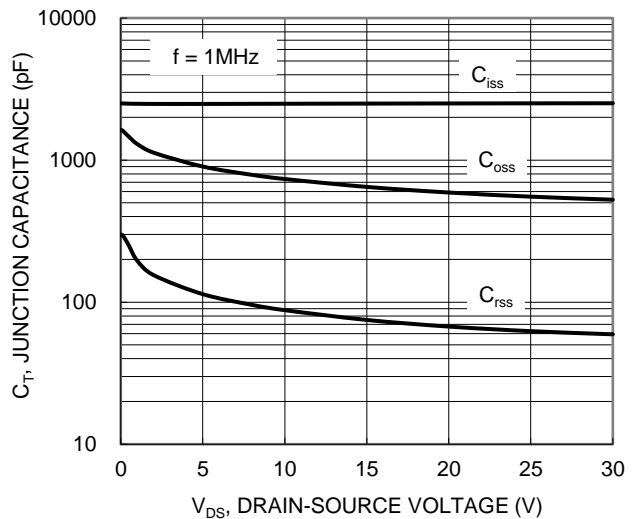


Figure 10. Typical Junction Capacitance

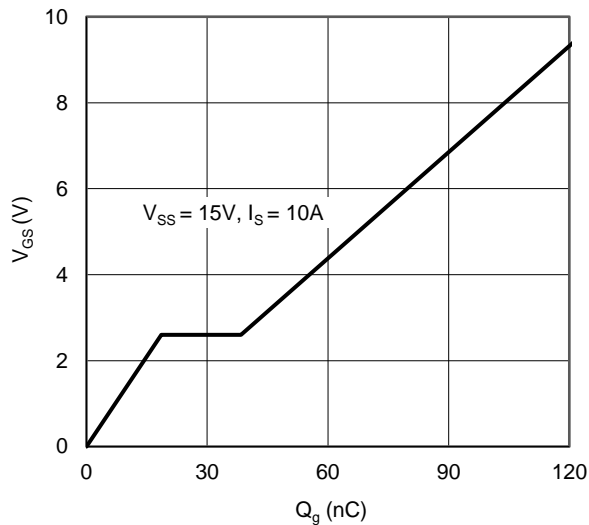


Figure 11. Gate Charge

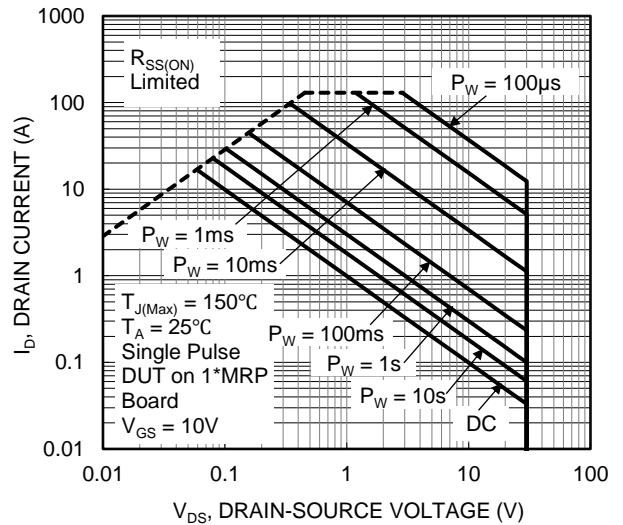


Figure 12. SOA, Safe Operation Area

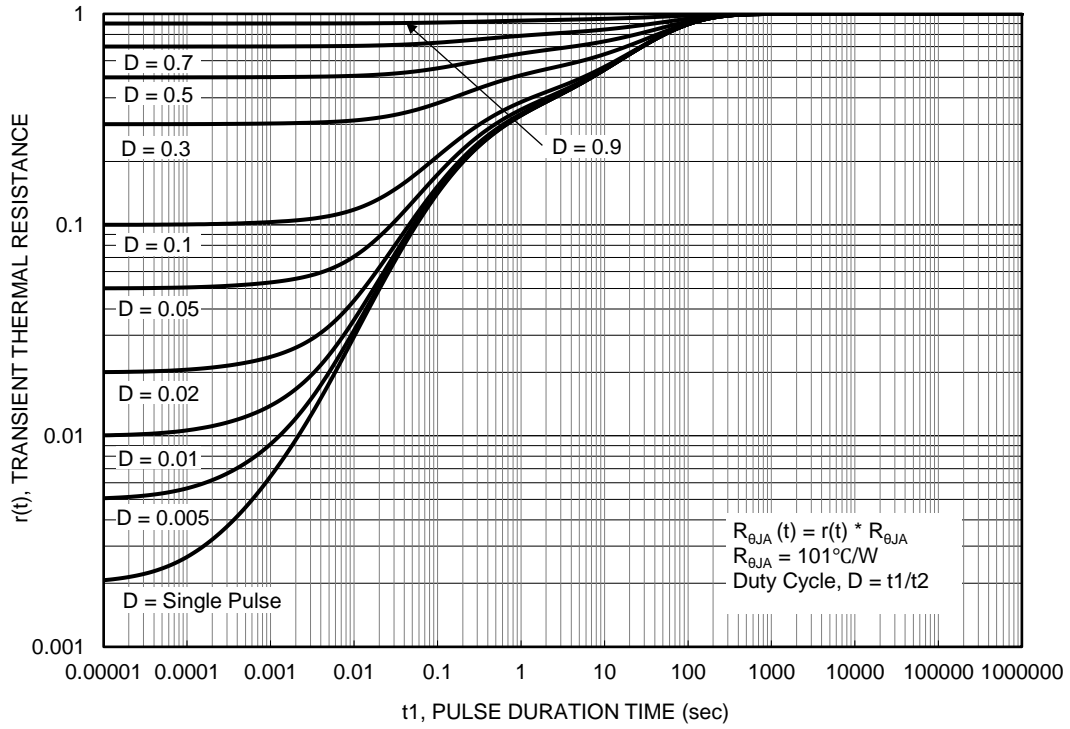
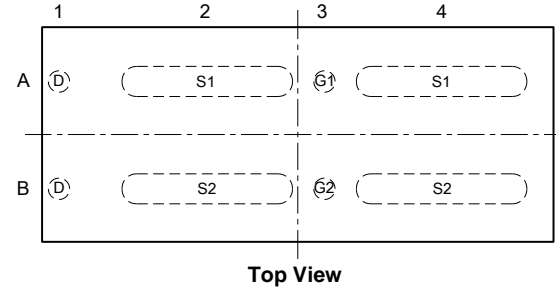
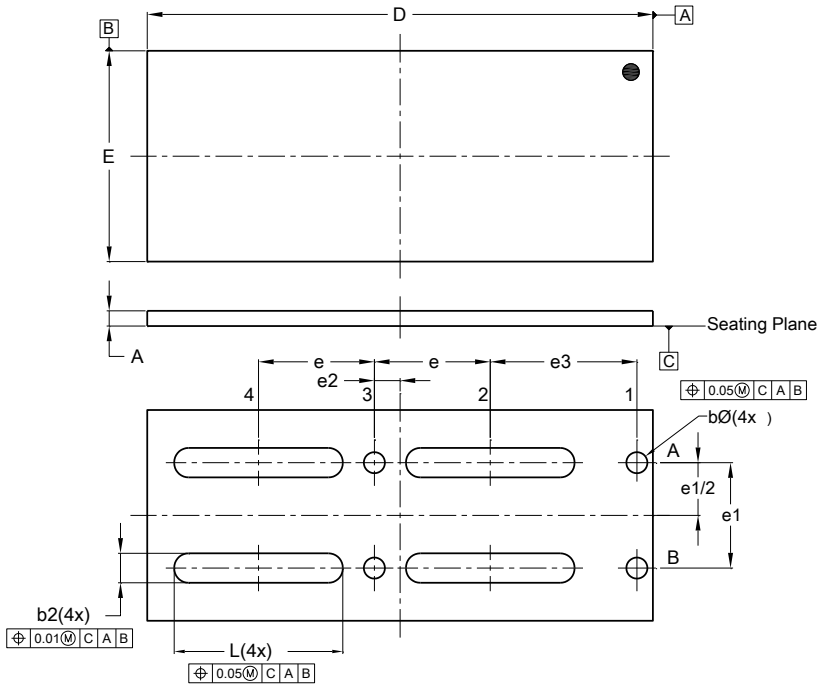


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X4-DSN6025-8



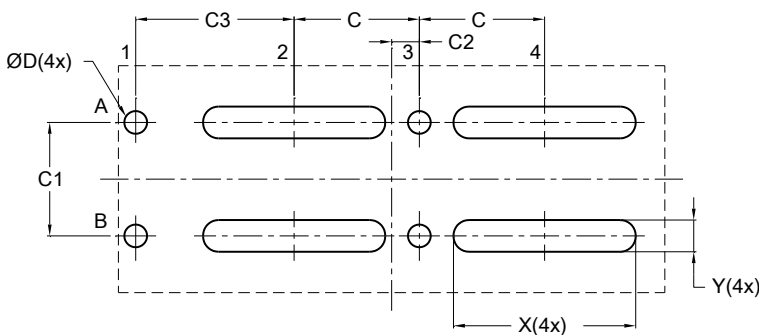
Pin Assignment			
A1	D	B1	D
A2	S1	B2	S2
A3	G1	B3	G2
A4	S1	B4	S2

X4-DSN6025-8			
Dim	Min	Max	Typ
A	0.14	0.22	0.18
b	--	--	0.25
b2	--	--	0.35
D	5.95	6.05	6.00
E	2.45	2.55	2.50
e	1.375 BSC		
e1	1.250 BSC		
e2	0.305 BSC		
e3	1.740 BSC		
L	1.97	2.03	2.00
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X4-DSN6025-8



Dimensions	Value (in mm)
C	1.375
C1	1.250
C2	0.305
C3	1.740
D	0.250
X	2.000
Y	0.350

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